

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chih Pin HUNG	07/27/2007
Chi Tsung CHIU	07/27/2007
IN DE OU	07/27/2007
Yung Hui WANG	07/27/2007
RECEIVING PARTY DATA	
Name:	ADVANCED SEMICONDUCTOR ENGINEERING, INC.
Street Address:	26, CHIN 3RD RD., NANTZE EXPORT PROCESSING ZONE
City:	KAOHSIUNG
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11870620
CORRESPONDENCE DATA	
Fax Number:	(703)518-5499
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	7036841111
Email:	awilson@ipfirm.com
Correspondent Name:	LOWE HAUPTMAN HAM AND BERNER
Address Line 1:	1700 DIAGONAL ROAD
Address Line 2:	SUITE 300
Address Line 4:	ALEXANDRIA, VIRGINIA 22314
ATTORNEY DOCKET NUMBER:	4459-244
NAME OF SUBMITTER:	Ayesha Wilson
Total Attachments: 1 source=Assignment#page1.tif	

OP \$40.00 11870620

PATENT

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REEL: 019948 FRAME: 0465

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) Chih Pin HUNG (4) Yung Hui WANG
 (2) Chi Tsung CHIU (5) _____
 (3) In De OU (6) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto

Advanced Semiconductor Engineering, Inc.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

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for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or

(a) for which an application for United States Letters Patent was executed on July 27, 2007,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside our signatures:

INVENTORS

1) Signature: Chih Pin HUNG
 Name: Chih Pin HUNG
 2) Signature: Chi Tsung CHIU
 Name: Chi Tsung CHIU
 3) Signature: In De OU
 Name: In De OU
 4) Signature: Yung Hui WANG
 Name: Yung Hui WANG
 5) Signature: _____
 Name: _____
 6) Signature: _____
 Name: _____

DATE SIGNED

July 27, 2007

July 27, 2007

July 27, 2007

July 27, 2007

PATENT**RECORDED: 10/11/2007****REEL: 019948 FRAME: 0466**